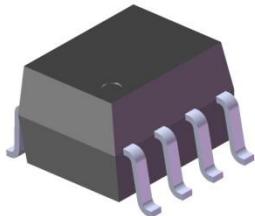


DATASHEET

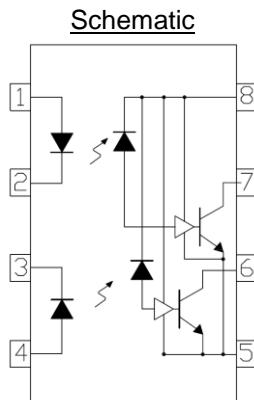
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8 PIN SOP DUAL CHANNEL HIGH SPEED 10MBit/s LOGIC GATE PHOTOCOUPLED EL063X Series



Features

- Compliance Halogen Free .
(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)
- High speed 10Mbit/s
- 10kV/ μ s min. common mode transient immunity (EL0631)
- Guaranteed performance from -40 to 85°C
- Wide operating temperature range of -40°C to 100°C
- Logic gate output
- High isolation voltage between input and output (Viso=3750 V rms)
- Compliance with EU REACH
- Pb free and RoHS compliant
- UL and cUL approved(No. E214129)
- VDE approved (No.40028116)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved



Pin Configuration

- 1. Anode
- 2. Cathode
- 3. Cathode
- 4. Anode
- 5. Gnd
- 6. Vout 2
- 7. Vout 1
- 8. Vcc

Description

The EL0630 and EL0631 are dual channel devices each consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a strobable output.

The devices are packaged in an 8-pin small outline package which conforms to the standard SO8 footprint.

Applications

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5 volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer peripheral interface

Truth Table (Positive Logic)

Input	Output
H	L
L	H

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Rating	Unit
Input	DC/ Average Forward current	I _F	20	mA
	Reverse voltage	V _R	5	V
	Power dissipation	P _D	45	mW
Output	Power dissipation	P _C	60	mW
	Output current	I _O	50	mA
	Output voltage	V _O	7.0	V
	Supply voltage (max 1 minute)	V _{CC}	7.0	V
Output Power Dissipation		P _O	80	mW
Isolation voltage ^{*1}		V _{ISO}	3750	V rms
Operating temperature		T _{OPR}	-40 ~ +100	°C
Storage temperature		T _{STG}	-55 ~ +125	°C
Soldering temperature ^{*2}		T _{SOL}	260	°C

Notes:

^{*1} AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3, 4 are shorted together, and pins 5, 6, 7, 8 are shorted together.

^{*2} For 10 seconds

Electrical Characteristics (Ta=-40 to 85°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	V _F	-	1.4	1.8	V	I _F =10mA
Reverse voltage	V _R	5.0	-	-	V	I _R =10μA
Temperature coefficient of forward voltage	ΔV _F /ΔT _A	-	-1.8	-	mV/°C	I _F =10mA
Input capacitance	C _{IN}	-	60	-	pF	V _F =0, f=1MHz

Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
High level supply current	I _{CCH}	-	13	18	mA	I _F =0mA, V _{CC} =5.5V
Low level supply current	I _{CCL}	-	15	21	mA	I _F =10mA, V _{CC} =5.5V

Transfer Characteristics (Ta=-40 to 85°C unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
HIGH Level Output Current	I _{OH}	-	-	100	μA	V _{CC} =5.5V, V _O =5.5V, I _F =250μA,
LOW Level Output Current	V _{OL}	-	-	0.6	V	V _{CC} =5.5V, I _F =5mA, I _{CL} =13mA
Input Threshold Current	I _{FT}	-	-	5	mA	V _{CC} =5.5V, V _O =0.6V, I _{OL} =13mA

Switching Characteristics (T_a=-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Propagation delay time to output High level ^{*4} (Fig.11)	t _{PHL}	-	-	100	ns	C _L =15pF, R _L =350Ω, T _A =25°C
Propagation delay time to output Low level ^{*5} (Fig.11)	t _{PLH}	-	-	100	ns	C _L =15pF, R _L =350Ω, T _A =25°C
Pulse width distortion	t _{PHL} - t _{PLH}	-	-	35	ns	C _L =15pF, R _L =350Ω
Output rise time ^{*6} (Fig.11)	t _r	-	40	-	ns	C _L =15pF, R _L =350Ω
Output fall time ^{*7} (Fig.11)	t _f	-	10	-	ns	C _L =15pF, R _L =350Ω
Common Mode Transient Immunity at Logic High ^{*8}	EL0630	5000			V/μs	I _F =0mA, V _{OH(MIN)} =2.0V, R _L =350Ω, T _A =25°C IV _{CMI} =1KV(Fig.12)
	EL0631	10000				I _F =0mA, V _{OH(MIN)} =2.0V, R _L =350Ω, T _A =25°C IV _{CMI} =1KV(Fig.12)
Common Mode Transient Immunity at Logic Low ^{*9}	EL0630	5000			V/μs	I _F =7.5mA, V _{OL(MAX)} =0.8V, R _L =350Ω, T _A =25°C IV _{CMI} =1KV(Fig.12)
	EL0631	10000				I _F =7.5mA, V _{OL(MAX)} =0.8V, R _L =350Ω, T _A =25°C IV _{CMI} =1KV(Fig.12)

Typical Electro-Optical Characteristics Curves

Fig.1 Input Diode Forward Voltage vs. Forward Current

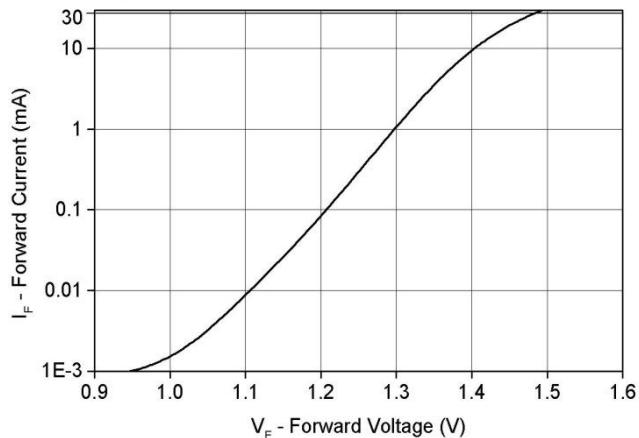


Fig.3 Low Level Output Current vs. Ambient Temperature

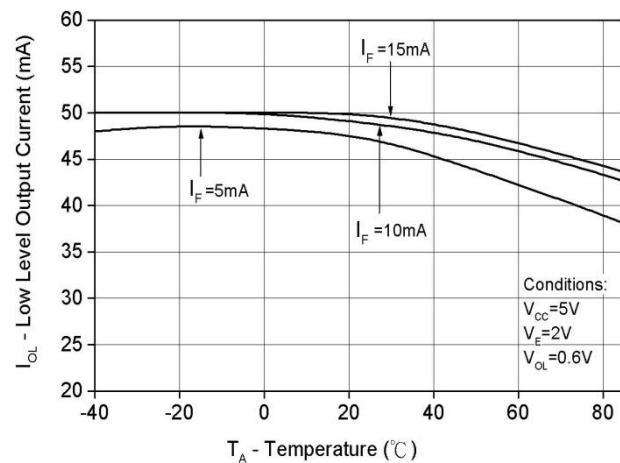


Fig.5 Output Voltage vs. Input Forward Current

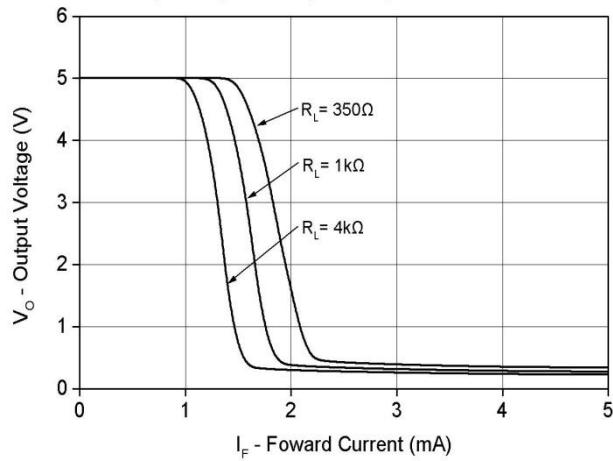


Fig.2 Low Level Output Voltage vs. Ambient Temperature

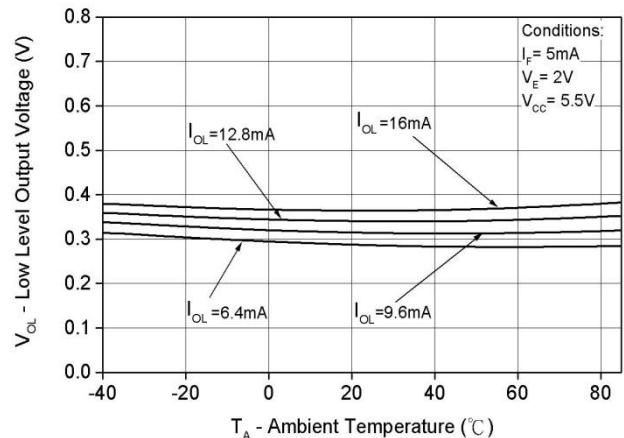


Fig.4 Input Threshold Current vs. Ambient Temperature

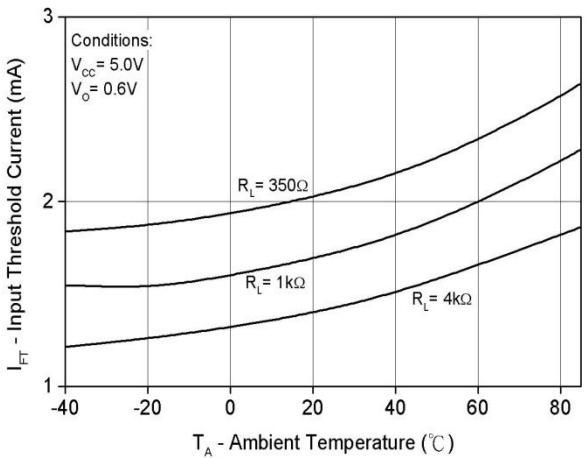


Fig.6 High Level Output Current vs. Temperature

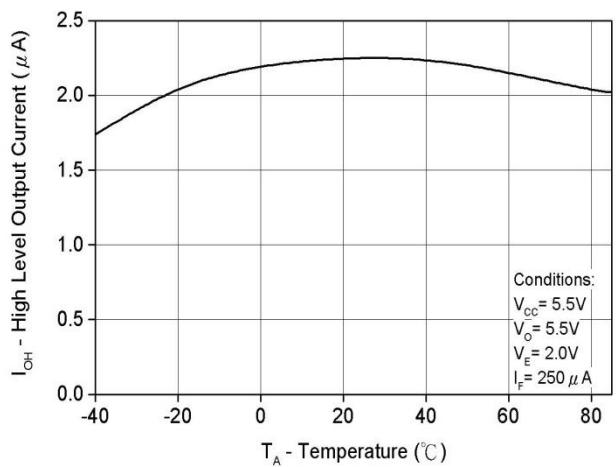


Fig.7 Switching Time vs. Forward Current

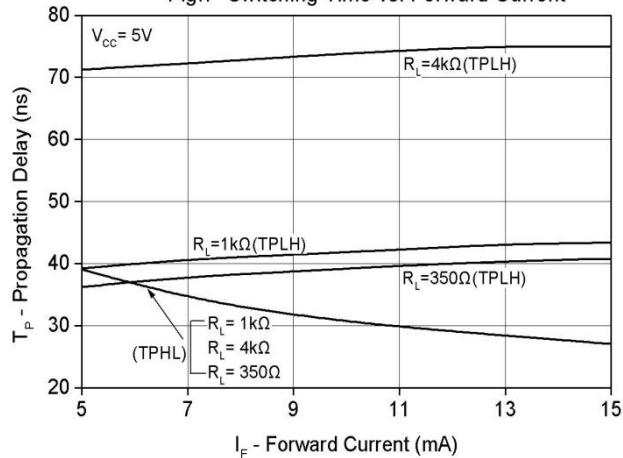


Fig.8 Switching Time vs. Temperature

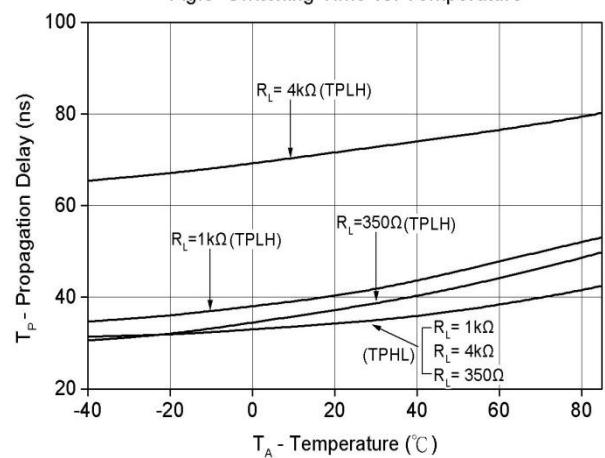


Fig.9 Pulse Width Distortion vs. Temperature

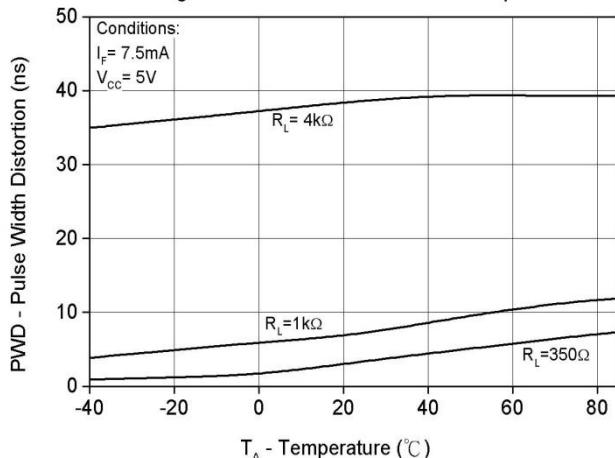


Fig.10 Rise and Fall Time vs. Temperature

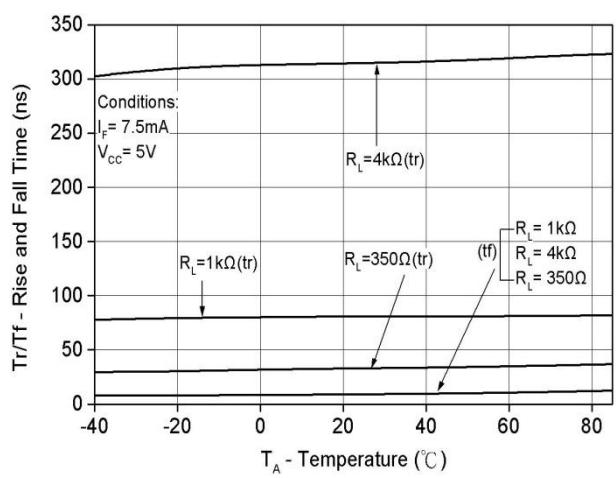


Fig. 11 Test circuit and waveforms for t_{PHL} , t_{PLH} , t_r , and t_f

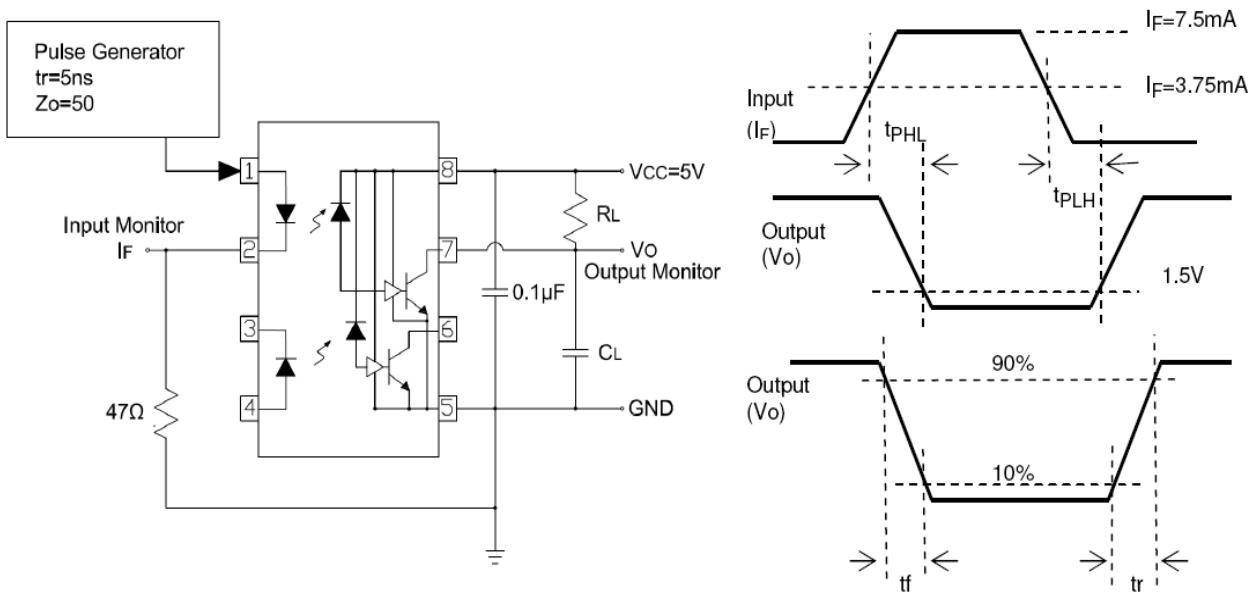
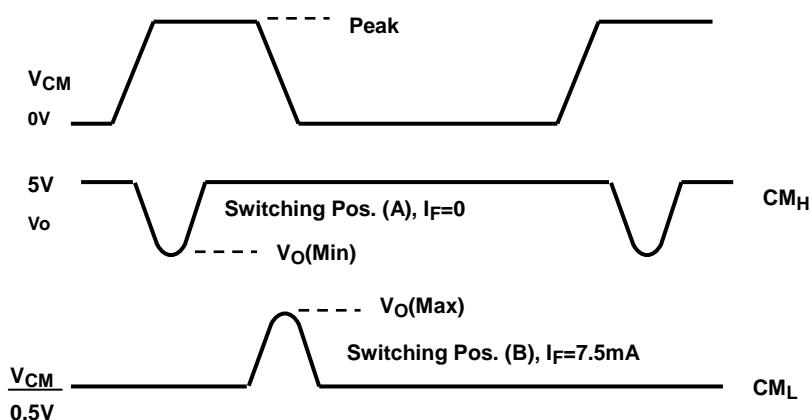
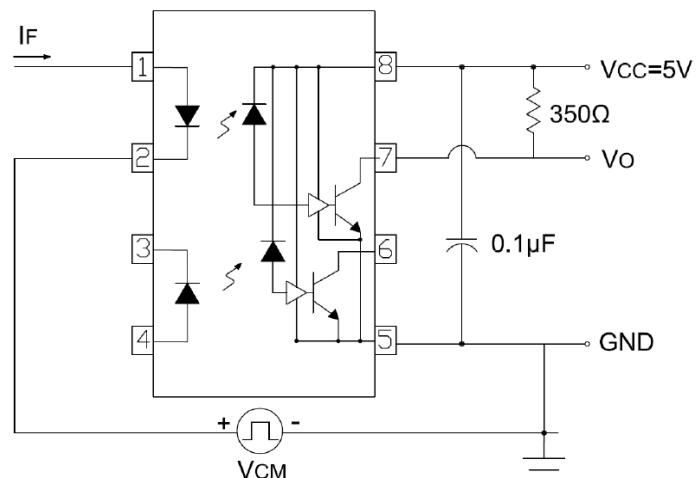


Fig. 12 Test circuit Common mode Transient Immunity



Notes

- *3 The V_{CC} supply must be bypassed by a $0.1\mu F$ capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package V_{CC} and GND pins
- *4. t_{PLH} – Propagation delay is measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
- *5. t_{PHL} – Propagation delay is measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
- *6. t_r – Rise time is measured from the 90% to the 10% levels on the LOW to HIGH transition of the output pulse.
- *7. t_f – Fall time is measured from the 10% to the 90% levels on the HIGH to LOW transition of the output pulse.
- *8 CM_H – The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., $V_{OUT} > 2.0V$).
- *9 CM_L – The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e., $V_{OUT} < 0.8V$).

Order Information

Part Number

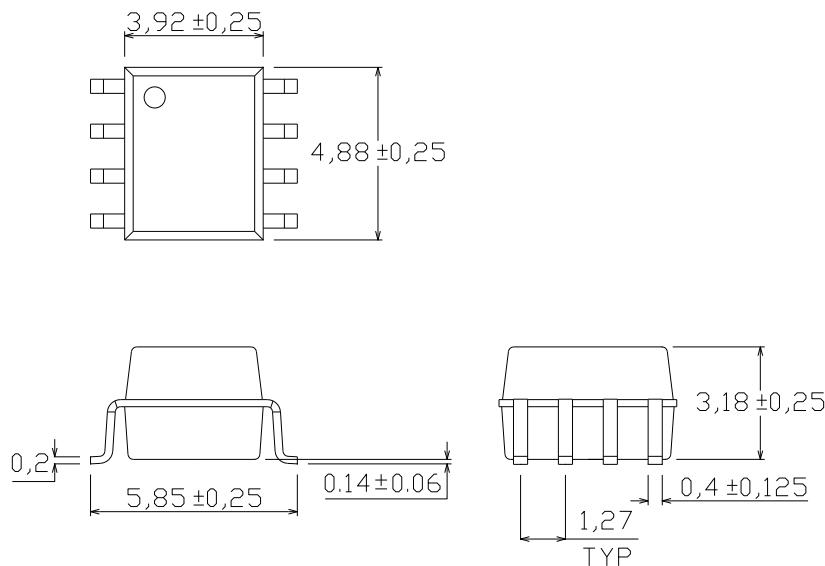
EL063X(Z)-V

Note

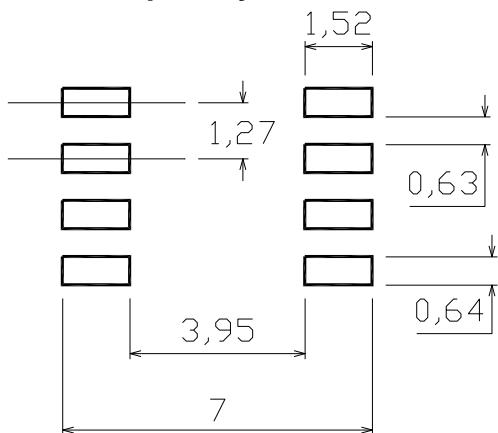
X = Part no. (X = 0 or 1)
Z = Tape and reel option (TA, TB or none).
V = VDE (optional)

Option	Description	Packing quantity
None	Standard	100 units per tube
-V	Standard + VDE	100 units per tube
(TA)	TA tape & reel option	2000 units per reel
(TB)	TB tape & reel option	2000 units per reel
(TA)-V	TA tape & reel option + VDE	2000 units per reel
(TB)-V	TB tape & reel option + VDE	2000 units per reel

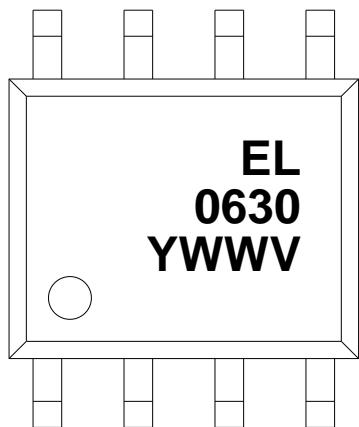
Package Dimension
(Dimensions in mm)



Recommended pad layout for surface mount leadform



Device Marking

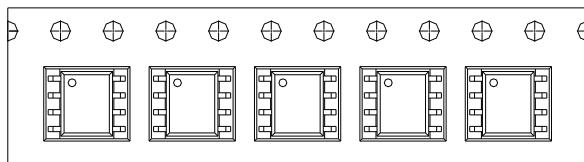


Notes

0630 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE (optional)

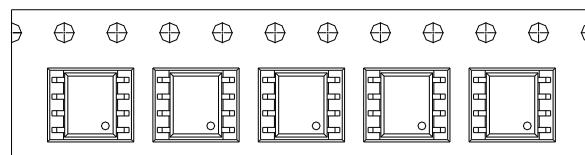
Tape & Reel Packing Specifications

Option TA



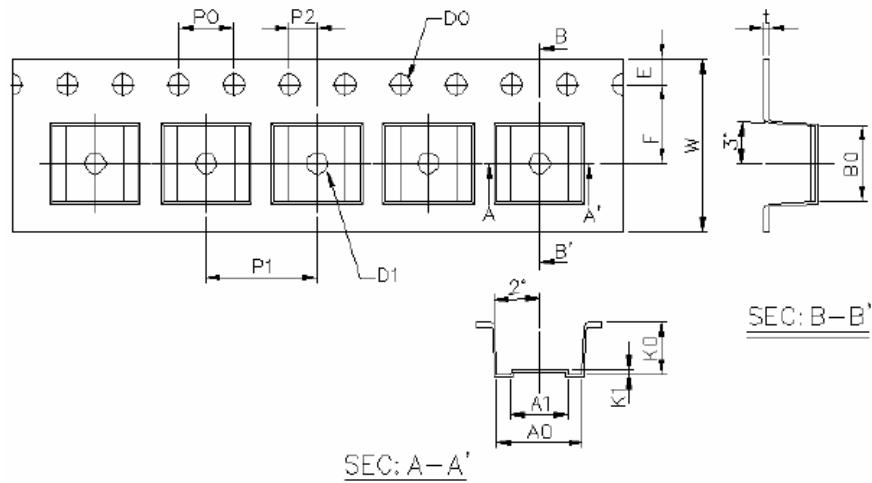
Direction of feed from reel

Option TB



Direction of feed from reel

Tape dimensions

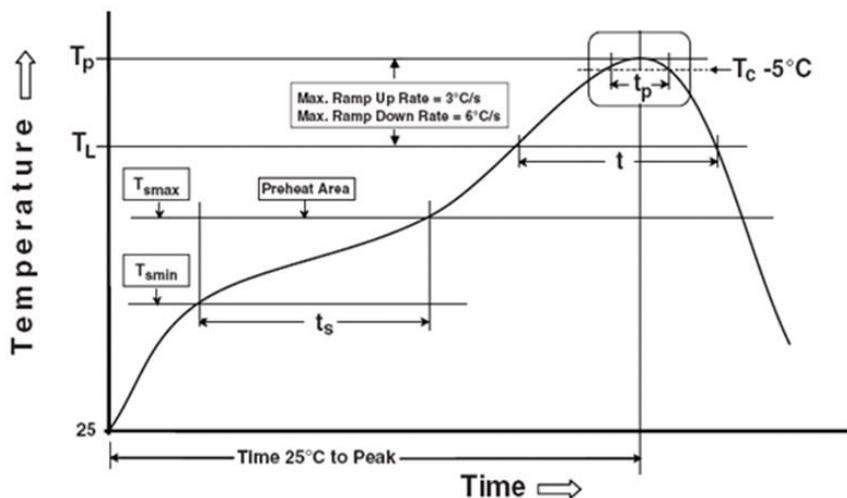


Dimension No.	A0	A1	B0	D0	D1	E	F
Dimension(mm)	6.2±0.1	4.1±0.1	5.28±0.1	1.5±0.1	1.5±0.3	1.75±0.1	5.5±0.1
Dimension No.	P0	P1	P2	t	W	K0	K1
Dimension(mm)	4.0±0.1	8.0±0.1	2.0±0.1	0.4±0.1	12.0+0.3/-0.1	3.7±0.1	0.3±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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